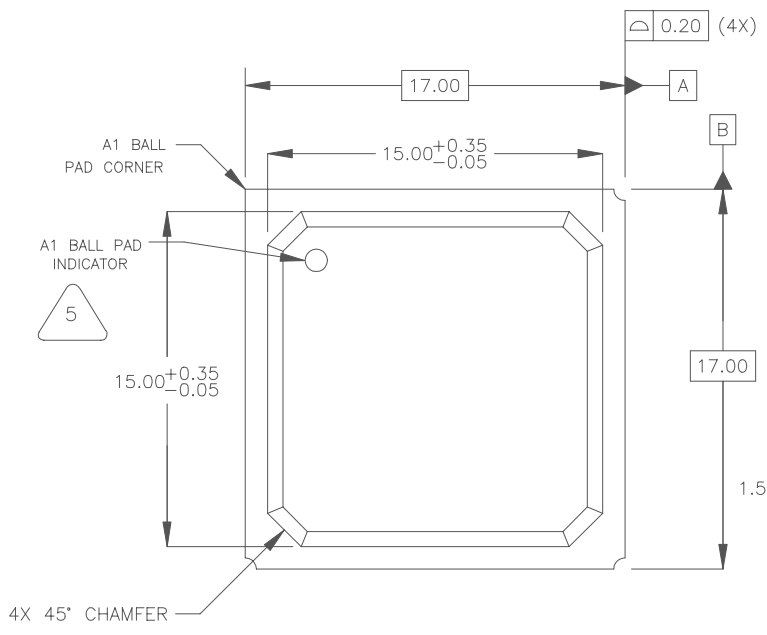
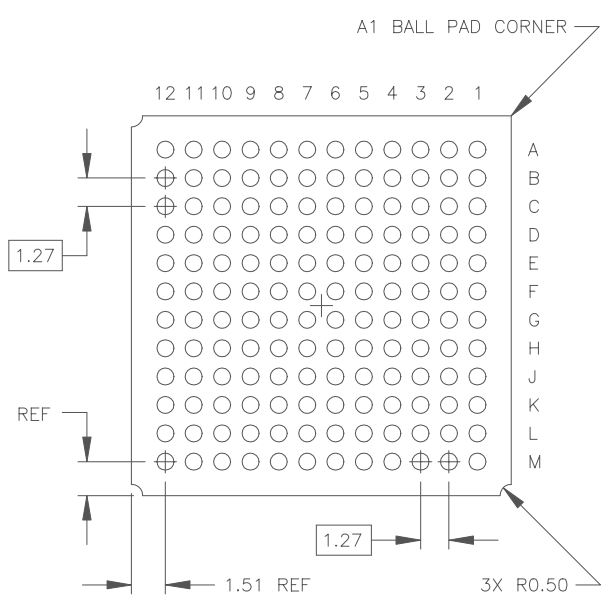


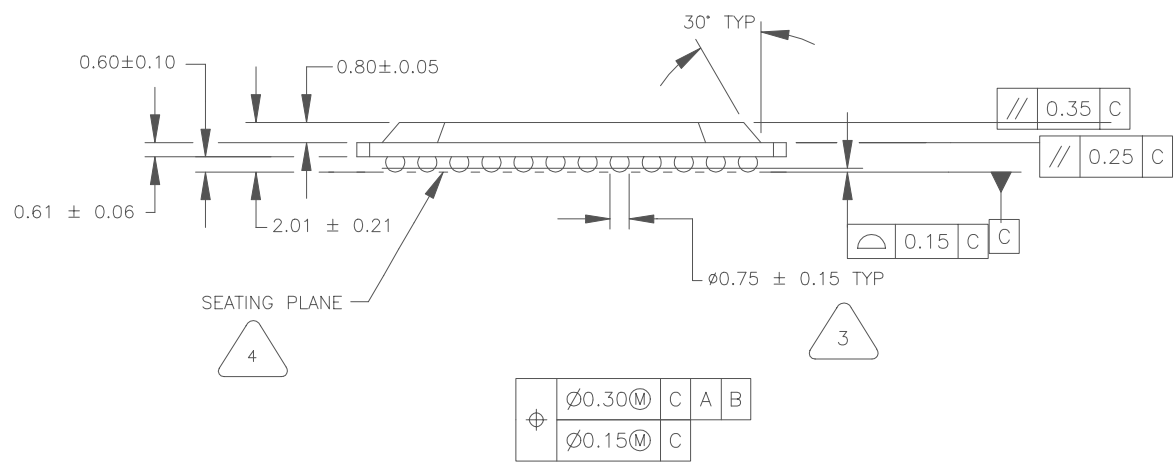
REVISIONS			
LTR.	DESCRIPTION	DATE	APPROVED
A	NEW DRAWING	12/02	



TOP VIEW



BOTTOM VIEW  
(BALL SIDE)



SIDE VIEW

NOTES:

- DIMENSION IS MM.
- THE BASIC SOLDER BALL GRID PITCH IS 1.27MM.
- DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.
- PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- A1 BALL PAD CORNER I.D.

SIGNATURE		DATE					
DOC. CONTROL:							
ENGR. MGR:				TITLE			
MFG. ENGR:				MARKETING OUTLINE DRAWING			
CHECKED BY:		DATE		17MM X 17MM, 144 BALLS, TE-PBGA, 4 LAYER			
DRAWN BY:		DATE		1.27 MM PITCH			
TWM		12/02		SIZE	FSCM NO.	PART NO.	REV.
JFD		12/02		A		56-G6020-001	A
SCALE				N/A		SHEET 1 of 1	